CAUI-4 Chip – Chip Spec Discussion

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Chip-Chip Considerations

- Target: low power, simple chip-chip specification to allow communication over TBD loss with one connector
 - Similar to Annex 83A in 802.3ba
 - 25cm or ~10 inches over PCB
 - If we apply 1.7dB loss / inch at 14GHz we get 17dB + Connector (~1dB)
 - Meg6_HighSR-Narrow (kochuparambil_01_0112)
 - Compare to OIF SR / MR
 - SR: 15.4dB
 - MR: ~20dB
 - ghiasi_02_0912_optx mentions 30cm
 - 18-20dB loss budget
- Potential differences with KR4:
 - Lower loss budget supports lower power, smaller receiver design
 - Reduced latency & complexity
 - No FEC
 - No in-band transmitter training
 - Adaptive Rx (SFP+)
 - Assume "system management"
 - Spec similar to 802.3ba CAUI



Interface Discussion & Implications

Chip-Chip

- If loss is kept to <20dB, there are potential implementations which avoid MTTFPA issue
 - CTLE designs are able to support greater than 10dB
 - Previous discussions had ~15dB loss
 - VSR 28G has 100mVpp eye opening at 1E-15
 - 802.3bj KR4 test 1 and 2 targeting 10⁻¹² with 16dB channel and high level of RMS broadband noise, 30dB with lower level of RMS broadband noise (without FEC)
 - High noise and high loss will be significantly relaxed for chip to chip

Table 93-7—Receiver interference tolerance parameters

Parameter	Test 1 values	Test 2 values	Test 3 values	Test 4 values	Units
Maximum BER without FEC	10-12	10-12	2 × 10 ⁻⁵	2 × 10 ⁻⁵	
Channel insertion loss at 12.89 GHz Real part of a_0 , min. * Real part of a_1 , min. Real part of a_2 , min. Real part of a_4 , min.	16 -0.1 -1.2 × 10 ⁻⁵ - -2.5 × 10 ⁻²¹	30 -0.1 -1.2 × 10 ⁻⁵ - -3.5 × 10 ⁻²¹	30 -0.1 -1.2 × 10 ⁻⁵ - -3.5 × 10 ⁻²¹	35 -0.1 -1.2 × 10 ⁻⁵ -5 × 10 ⁻²¹	dB Hz ^{-1/2} Hz ⁻¹ Hz ⁻²
Applied peak-to-peak sinusoidal jitter ^b	0.115	0.115	0.115	0.115	UI
Applied peak-to-peak random jitter	0.15	0.15	0.15	0.15	UI
Applied even-odd jitter	0.035	0.035	0.035	0.035	UI
Applied RMS broadband noise	10	2.8	6.3	3.2	mV

^{*}For each test channel, a_0 is limited to a maximum value of 0.1 and a_1 , a_2 , and a_4 are limited to a maximum value of 0. There is no minimum value energified for a_1



The frequency of the sinusoid must be greater than 100 MH:

Random Jitter is specified at a BER of 10^{-12} .

CAUI-4 Chip-Chip transmitter considerations

	KR4 (D1.2, TP2)	MR	CAUI-4 Chip-Chip Potential
Signaling rate, per lane	25.78125+/-100ppm	19.6 – 28.05	25.78125+/-100ppm
Unit Interval	38.787879ps	35.65ps - 51ps	38.787879ps
Differential peak-to-peak output voltage (max) with Tx disabled	30mV		30mVppd
Common Mode Voltage (max)	1.9V	1.7V	1.9V
Common Mode Voltage (min)	OV	-0.1V	OV
Differential output return loss (min)	RL(f) >= - 10log10((449.7+f^2)/(3671+f^2))	A0 = -12 fo = 50MHz f1 = 4.4189 f2 = 25.78125 Slope = 12dB/dec	RL(f) >= - 10log10((449.7+f^2)/(3671+f^2)), 0.05<=f<=13GHz
Common mode output returnloss (min)	RL(f)>= 6dB, 0.05<=f<=13GHz	-6dB , f<10GHz -4dB, 10G <f<25.78125ghz< td=""><td>RL(f)>= 6dB, 0.05<=f<=13GHz</td></f<25.78125ghz<>	RL(f)>= 6dB, 0.05<=f<=13GHz
Common-mode AC output voltage (max,rms)	12mV	12mV	12mV
Amplitude peak-to-peak (max)	1200mV	1200mV	1200mV
Amplitude peak-to-peak (min)		800mV	800mV



CAUI-4 Chip-Chip transmitter considerations

	KR4 (D1.2, TP2)	MR	CAUI-4 Chip-Chip Potential
Transmitter steady state voltage	0.4 (min) - 0.6V (max)		TBD
Linear fit pulse (min)	0.8 x Transmitter steady state voltage		TBD
Transmitted wave form Max RMS normalized error (linear fit), "e" abs coefficient step size (min.) abs coefficient step size (max.) Pre-cursor full-scale range (min.) Post-cursor full-scale range (min.)	0.037 0.0083 0.05 1.54 4	C-1: -20 to 0 C1: -25 to 0 C0: 40 to 100 Step size: 1.25 to 5	TBD
Far end transmit output noise (max)	2mV (low loss channel) 1mV (high loss channel)		TBD
Output jitter (max)	Effective RJ: 0.15UI Even-odd jitter: 0.035UI TJ excluding DDJ: 0.28UI	TUUGJ = 0.15Ulpp T_UBHPJ = 0.15Ulpp T_DCD = 0.035Ulpp TJ = 0.28Ulpp	Effective RJ = 0.15Ulpp Even-odd jitter = 0.035Ulpp TJ = 0.28Ulpp
Differential Resistance		80 ohms min, 100ohms typ, 120 ohms max	TBD
Transition time (min, 20/80%)	8ps	8ps	8ps



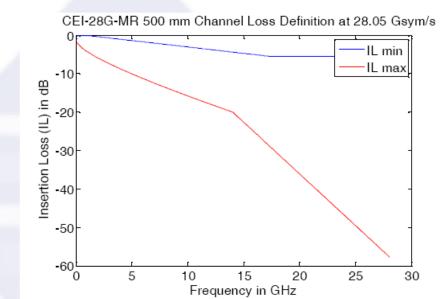
CAUI-4 Chip-Chip Receiver considerations

	KR4 (D1.2, TP2)	MR	CAUI-4 Chip-Chip Potential
Differential Input Return loss (min)	RL(f) >= - 10log10((449.7+f^2)/(3671+f^2))	A0 = -12 fo = 50MHz f1 = 4.4189 f2 = 25.78125 Slope = 12dB/dec	RL(f) >= - 10log10((449.7+f^2)/(3671+f^2)), 0.05<=f<=13GHz
Common mode input return loss (min)	RL(f) >=6dB, 0.05<=f<=13GHz	6dB , f<10GHz -4dB, 10G <f<25.78125ghz< td=""><td>RL(f) >=6dB, 0.05<=f<=13GHz</td></f<25.78125ghz<>	RL(f) >=6dB, 0.05<=f<=13GHz
Differential to common-mode return loss (min)	TBD		TBD
Input Differential Voltage (max)		1200	1200mV
Differential Impedance		80ohms min, 100ohms typical, 120ohms max	TBD
Input Impedance Mismatch (max)		10%	TBD
Input common mode voltage		-200mV (min), 1800mV (max)	TBD



OIF MR ILmin/max

Channel ILmin and ILmax Graph



$$IL_{\max} = \begin{cases} 1.083 + 2.436 \sqrt{\frac{f \times 28.05}{f_b}} + 0.698 \frac{f \times 28.05}{f_b}, & f_{\min} \le f < \frac{f_b}{2} \\ -17.783 + 2.694 \frac{f \times 28.05}{f_b}, & \frac{f_b}{2} \le f \le f_b \end{cases}$$

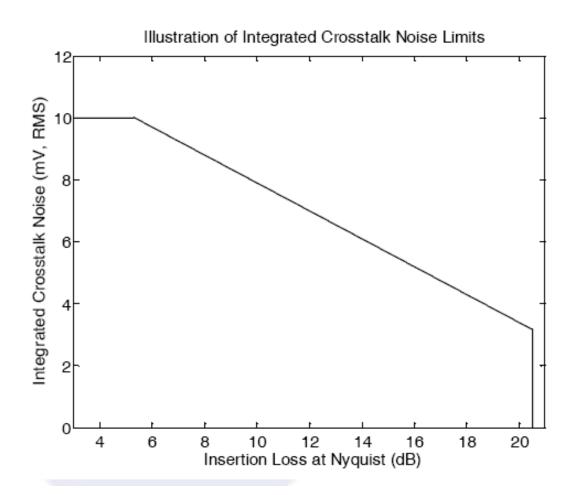
$$_{\Box}$$
 IL_{max} (14.025 GHz) = -20 dB

OIF MR fitted IL parameters

Parameter	Units	Value	
		Min	Max
Minimum Frequency	GHz	0.05	
Maximum Frequency	GHz		25.78
Fitted Insertion Loss At Nyquist	dB		20
Fitted Insertion loss a0	dB		2
Fitted insertion loss a1	dB		14.914
Fitted Insertion loss a2	dB		41.288
Fitted insertion loss a4	dB		19.728



OIF MR ICN



Receiver Interference Tolerance

Parameter	Test 1 values	Test 2 values
Maximum BER*	10-12	10 ⁻¹²
Channel Insertion Loss at 12.89GHz	TBD	TBD
Applied peak-to-peak sinusoidal jitter	TBD	TBD
Applied peak-to-peak random jitter	TBD	TBD
Applied even-odd jitter	TBD	TBD
Applied RMS broadband noise	TBD	TBD

^{*} Maximum BER assumes errors are not correlated to ensure a sufficiently high mean time to false packet acceptance assuming 64b/66b coding. Actual implementation of the receiver is beyond the scope of the standard.

Compliance points

- See 93.8.2.1 Receiver test fixture from 802.3bj
- See 93.8.1.1 Transmitter test fixture from 802.3bj

Summary

- 802.3bm chip-to-chip has a significant amount of material that can be leveraged (802.3bj, OIF, etc)
 - Preliminary feedback from system vendors has been to leverage as much as possible
- CAUI-4 ad hoc group is collecting input to ensure appropriate application targets are met while achieving expected economies relative to 100GBASE-KR4
- Baseline focus areas include:
 - channel requirements
 - receiver interference tolerance
 - transmitter waveform specification
 - MTTFPA robustness